EXHIBIT 13 APPENDIX C: T-COIL DATA PLOT

CELL BC-0

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_S2151_TCoil_CELL-BC0_Ch.1013 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ▢▢▢ 1 deg C, Liquid T = 22.0 ▢▢▢ 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.2 dB
ABM1 comp = 0.448 dB A/m
BWC Factor = 0.155041 dB
Location: 0.8, 0, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
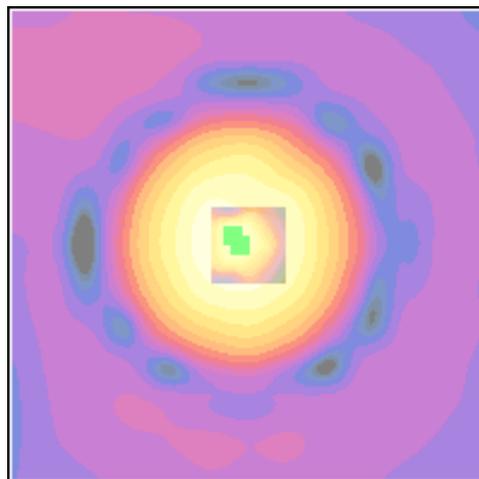Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.4 dB
ABM1 comp = 0.649 dB A/m
BWC Factor = 0.155041 dB
Location: 1.6, -1, 3.7 mm

0 dB = 456.1

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC0 _Ch. 1013 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.1 dB
ABM1 comp = -7.22 dB A/m
BWC Factor = 0.155041 dB
Location: 7.9, 0, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
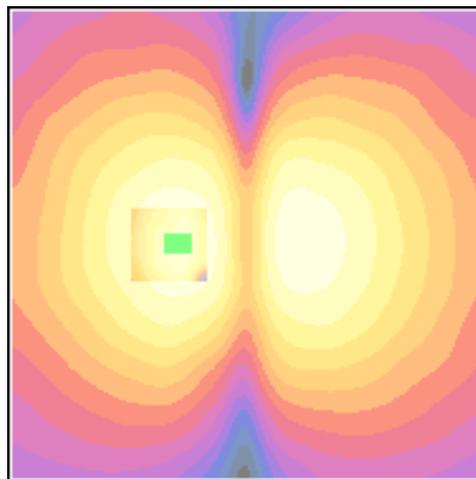Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.9 dB
ABM1 comp = -7.32 dB A/m
BWC Factor = 0.155041 dB
Location: 6.9, 0, 3.7 mm

0 dB = 321.1

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC0 _Ch. 1013 y (transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.9 dB
ABM1 comp = -7.70 dB A/m
BWC Factor = 0.155041 dB
Location: 1.3, -7.5, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
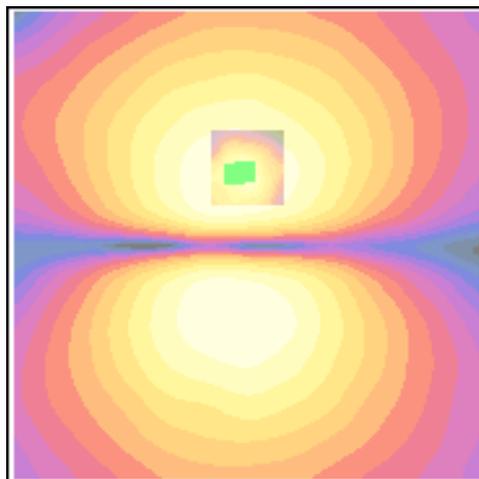Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.0 dB
ABM1 comp = -7.66 dB A/m
BWC Factor = 0.155041 dB
Location: 0.2, -7.9, 3.7 mm

0 dB = 280.0

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC0_Ch.384 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.0 dB
ABM1 comp = 0.339 dB A/m
BWC Factor = 0.155041 dB
Location: 0.8, 0, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
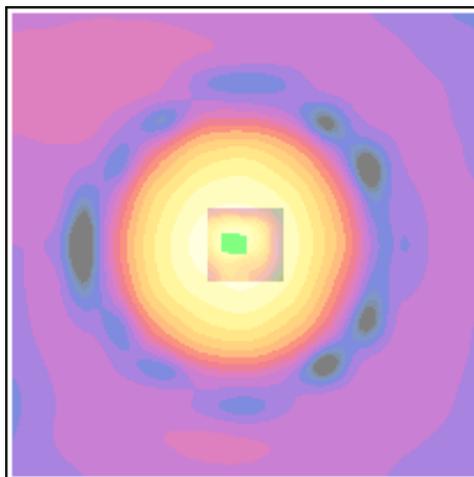Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.2 dB
ABM1 comp = 0.595 dB A/m
BWC Factor = 0.155041 dB
Location: 1.6, -0.2, 3.7 mm

0 dB = 448.0

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC0 _Ch.384 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.5 dB
ABM1 comp = -7.84 dB A/m
BWC Factor = 0.155041 dB
Location: 7.9, 0, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
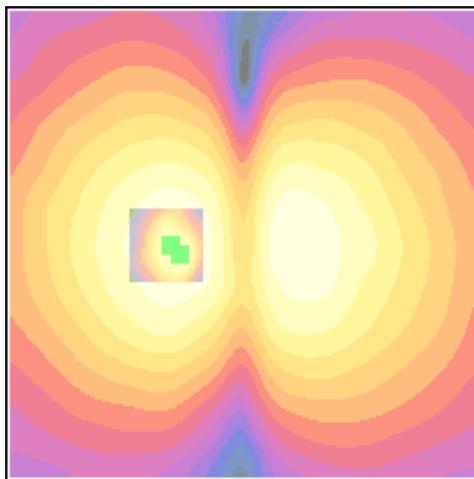Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.8 dB
ABM1 comp = -7.49 dB A/m
BWC Factor = 0.155041 dB
Location: 6.9, 1, 3.7 mm

0 dB = 297.9

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC0 _Ch.384 y(transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ⬚⬚⬚ 1 deg C, Liquid T = 22.0 ⬚⬚⬚ 1 deg C

General Scans_384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -7.55 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -5.8, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
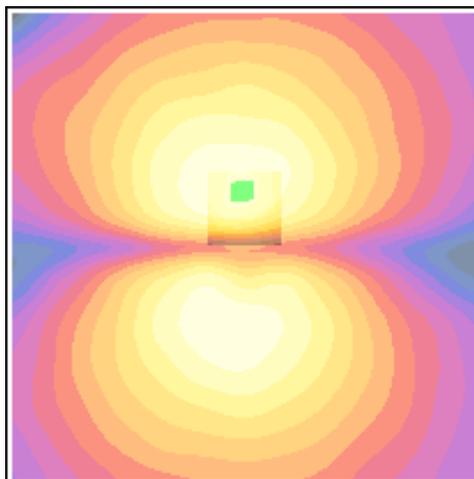Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.5 dB
ABM1 comp = -7.21 dB A/m
BWC Factor = 0.155041 dB
Location: 0, -6.1, 3.7 mm

0 dB = 287.4

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC0_Ch. 777 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.2 dB
ABM1 comp = 0.438 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, 0.4, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
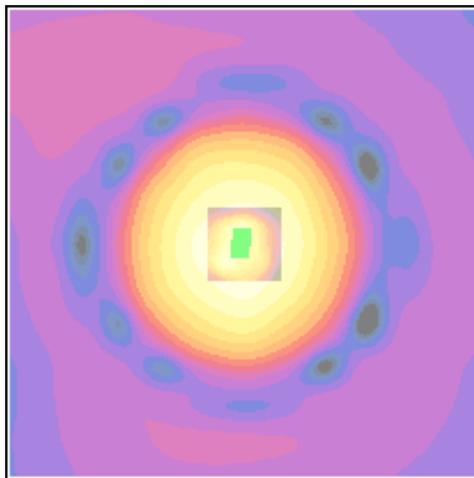Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.3 dB
ABM1 comp = 0.499 dB A/m
BWC Factor = 0.155041 dB
Location: 0.2, -0.8, 3.7 mm

0 dB = 455.2

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL- BC0_Ch. 777 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.7 dB
ABM1 comp = -7.65 dB A/m
BWC Factor = 0.155041 dB
Location: 6.3, 0.4, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
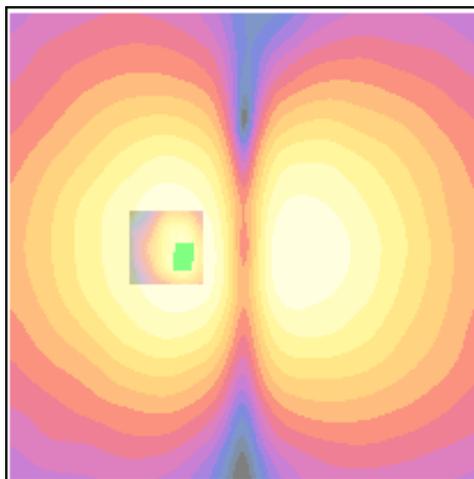Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.9 dB
ABM1 comp = -7.33 dB A/m
BWC Factor = 0.155041 dB
Location: 6.5, 1.4, 3.7 mm

0 dB = 304.1

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL- BC0_Ch. 777 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -7.39 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, 8.3, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
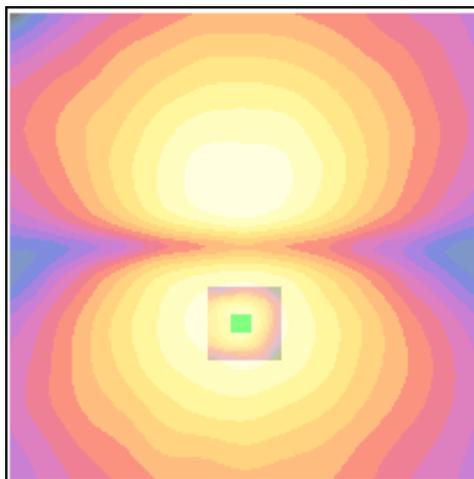Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.4 dB
ABM1 comp = -7.35 dB A/m
BWC Factor = 0.155041 dB
Location: 0.2, 8.3, 3.7 mm

0 dB = 288.4

CELL-BC10

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 476 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_476/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.2 dB
ABM1 comp = 0.164 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, 0.4, 3.7 mm

General Scans_476/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
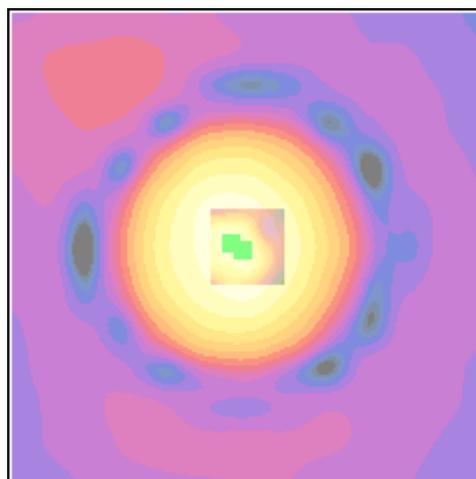Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.3 dB
ABM1 comp = 0.403 dB A/m
BWC Factor = 0.155041 dB
Location: 1.8, -0.4, 3.7 mm

0 dB = 459.1

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 476 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ⊡⊡⊡ 1 deg C, Liquid T = 22.0 ⊡⊡⊡ 1 deg C

General Scans_476/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.7 dB
ABM1 comp = -7.69 dB A/m
BWC Factor = 0.155041 dB
Location: 7.9, 0, 3.7 mm

General Scans_476/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
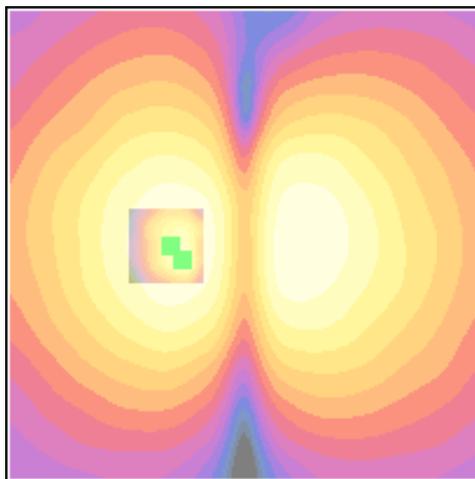Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.1 dB
ABM1 comp = -7.36 dB A/m
BWC Factor = 0.155041 dB
Location: 6.7, 1.6, 3.7 mm

0 dB = 307.2

Test Laboratory: COMPTEST/KYOCERA

Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 476 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_476/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.9 dB
ABM1 comp = -8.18 dB A/m
BWC Factor = 0.155041 dB
Location: 0, -5.8, 3.7 mm

General Scans_476/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
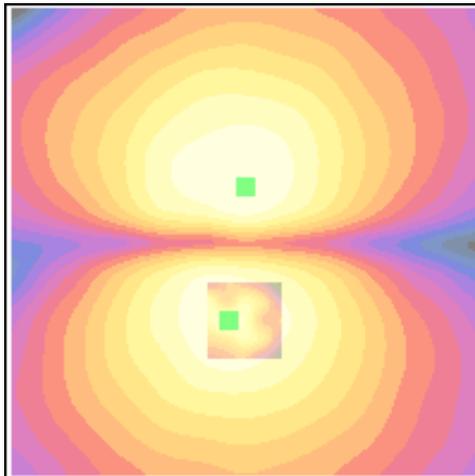Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.7 dB
ABM1 comp = -7.78 dB A/m
BWC Factor = 0.155041 dB
Location: 1.8, 8.3, 3.7 mm

0 dB = 279.3

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 580 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_580/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.5 dB
ABM1 comp = -0.148 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 0.8, 3.7 mm

General Scans_580/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
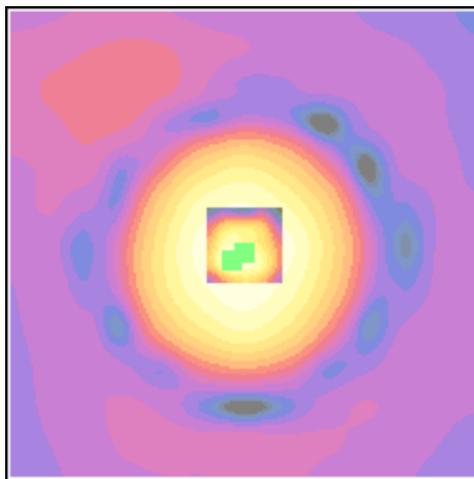Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.4 dB
ABM1 comp = 0.632 dB A/m
BWC Factor = 0.155979 dB
Location: 1.4, 1.6, 3.7 mm

0 dB = 423.9

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 580 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_580/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.1 dB
ABM1 comp = -7.46 dB A/m
BWC Factor = 0.155979 dB
Location: 5.8, 0.4, 3.7 mm

General Scans_580/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
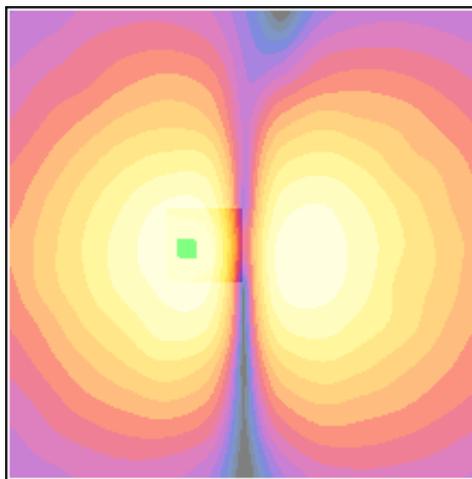Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.1 dB
ABM1 comp = -7.51 dB A/m
BWC Factor = 0.155979 dB
Location: 6.2, 0.4, 3.7 mm

0 dB = 321.2

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 580 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ⬚⬚⬚ 1 deg C, Liquid T = 22.0 ⬚⬚⬚ 1 deg C

General Scans_580/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.9 dB
ABM1 comp = -8.06 dB A/m
BWC Factor = 0.155979 dB
Location: -0.4, 9.2, 3.7 mm

General Scans_580/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
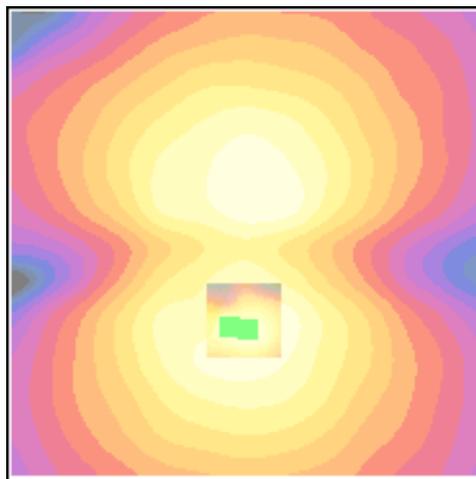Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.0 dB
ABM1 comp = -7.61 dB A/m
BWC Factor = 0.155979 dB
Location: 1.6, 8.9, 3.7 mm

0 dB = 278.0

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 684 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ⬜⬜⬜ 1 deg C, Liquid T = 22.0 ⬜⬜⬜ 1 deg C

General Scans_684/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.5 dB
ABM1 comp = -0.580 dB A/m
BWC Factor = 0.155979 dB
Location: 1.7, 0, 3.7 mm

General Scans_684/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
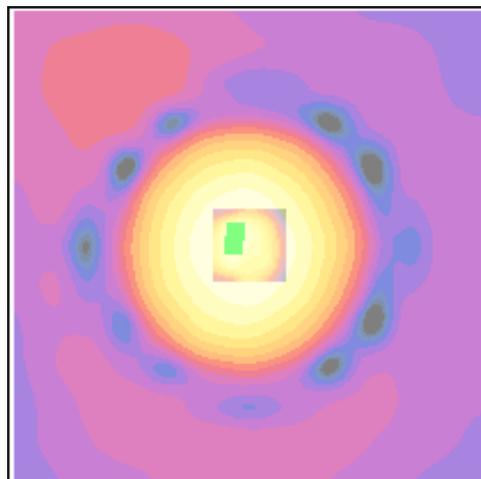Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.5 dB
ABM1 comp = 0.087 dB A/m
BWC Factor = 0.155979 dB
Location: 1.4, -1.4, 3.7 mm

0 dB = 422.1

Test Laboratory: COMPTEST/KYOCERA

Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 684 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ⬜⬜⬜ 1 deg C, Liquid T = 22.0 ⬜⬜⬜ 1 deg C

General Scans_684/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.4 dB
ABM1 comp = -8.53 dB A/m
BWC Factor = 0.155979 dB
Location: -5.4, 0.4, 3.7 mm

General Scans_684/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
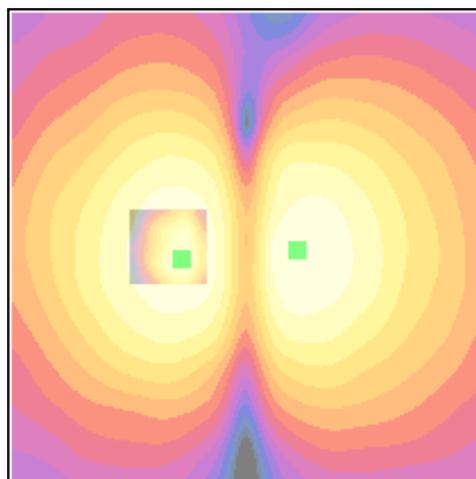Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.8 dB
ABM1 comp = -7.71 dB A/m
BWC Factor = 0.155979 dB
Location: 6.9, 1.4, 3.7 mm

0 dB = 294.2

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_CELL-BC10_Ch. 684 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_684/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.1 dB
ABM1 comp = -7.81 dB A/m
BWC Factor = 0.155979 dB
Location: 1.7, -5.4, 3.7 mm

General Scans_684/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
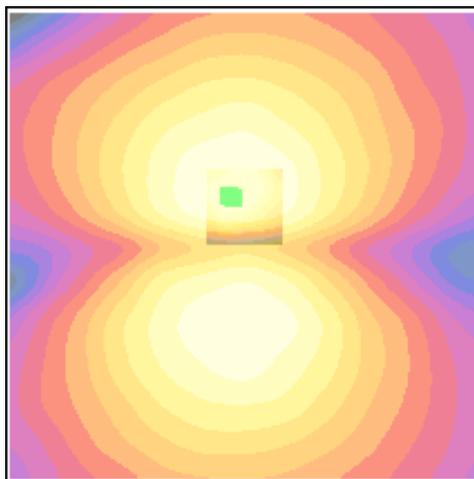Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.5 dB
ABM1 comp = -7.49 dB A/m
BWC Factor = 0.155979 dB
Location: 1.2, -5.2, 3.7 mm

0 dB = 284.4

PCS

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_PCS_Ch. 25 z(axial)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
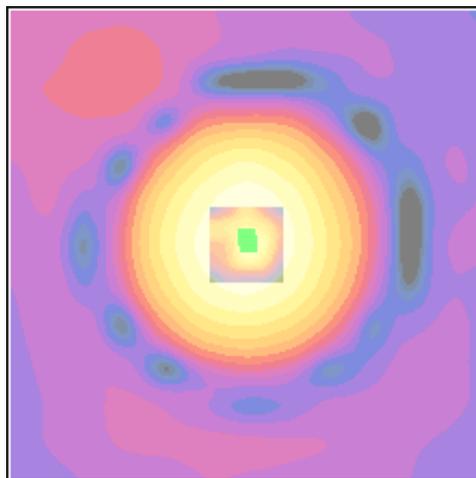Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.1 dB
ABM1 comp = -0.619 dB A/m
BWC Factor = 0.155041 dB
Location: 0, -0.8, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.5 dB
ABM1 comp = -0.631 dB A/m
BWC Factor = 0.155041 dB
Location: -0.2, 0, 3.7 mm

0 dB = 404.2

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_PCS_ Ch. 25 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.1 dB
ABM1 comp = -8.76 dB A/m
BWC Factor = 0.155041 dB
Location: 7.5, -0.4, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
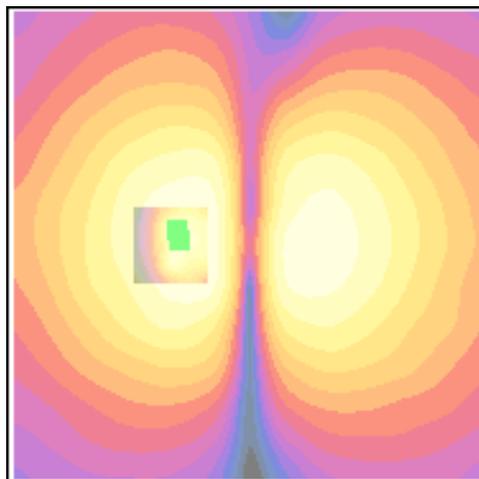Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.0 dB
ABM1 comp = -8.79 dB A/m
BWC Factor = 0.155041 dB
Location: 7.7, -1.6, 3.7 mm

0 dB = 285.8

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_PCS_ Ch. 25 y(transversal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, εr = 1; ρ = 0 kg/m3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
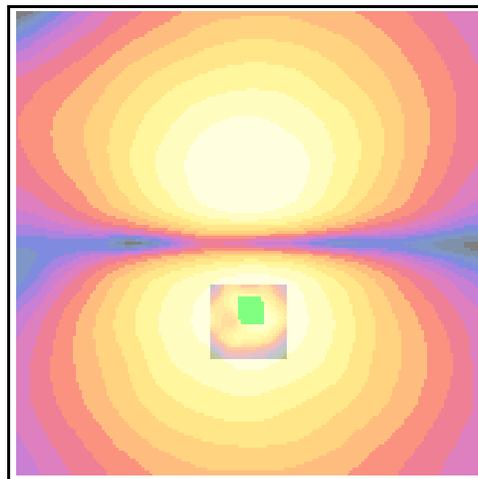Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.1 dB
ABM1 comp = -8.94 dB A/m
BWC Factor = 0.155041 dB
Location: -0.4, 7.5, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -8.88 dB A/m
BWC Factor = 0.155041 dB
Location: -0.2, 6.9, 3.7 mm

0 dB = 254.7

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2150_TCoil_PCS Ch. 600 z(axial)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.9 dB
ABM1 comp = -0.421 dB A/m
BWC Factor = 0.155979 dB
Location: 0, -1.7, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
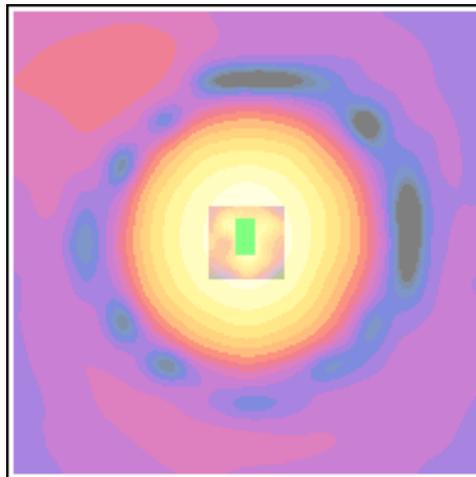Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.5 dB
ABM1 comp = -0.479 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 0.2, 3.7 mm

0 dB = 392.7

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_PCS Ch. 600 x (longitudinal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
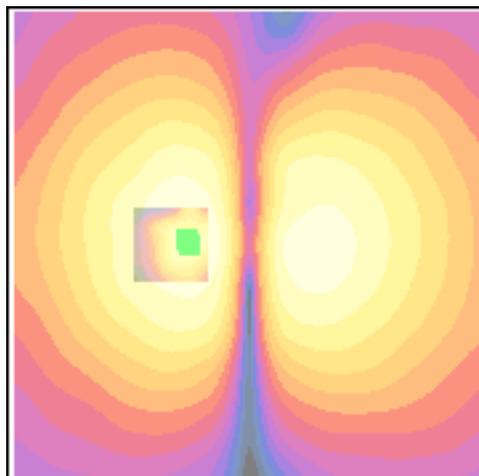**Cursor:**
ABM1/ABM2 = 49.2 dB
ABM1 comp = -8.53 dB A/m
BWC Factor = 0.155979 dB
Location: 6.7, -0.4, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -8.37 dB A/m
BWC Factor = 0.155979 dB
Location: 6.3, 0, 3.7 mm

0 dB = 287.1

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_PCS_ Ch. 600 y(transversal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
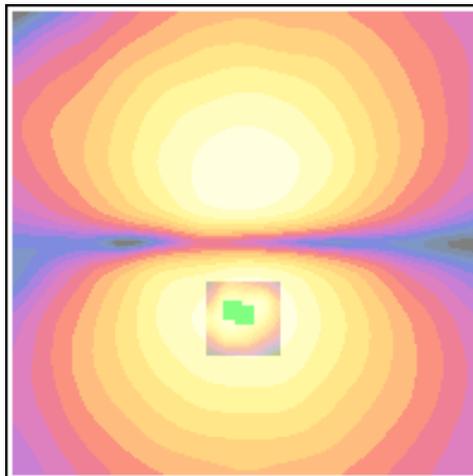Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.8 dB
ABM1 comp = -8.57 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 7.9, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.1 dB
ABM1 comp = -8.70 dB A/m
BWC Factor = 0.155979 dB
Location: 1.4, 7.3, 3.7 mm

0 dB = 274.2

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2150_TCoil_PCS_ Ch.1175 z(axial)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ⯀⯀⯀ 1 deg C, Liquid T = 22.0 ⯀⯀⯀ 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.2 dB
ABM1 comp = -0.527 dB A/m
BWC Factor = 0.155041 dB
Location: 0, 0, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
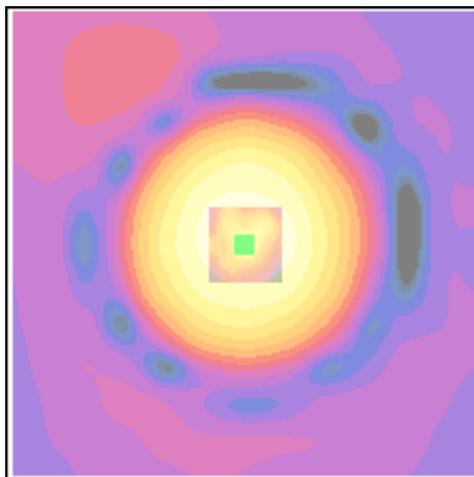Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.3 dB
ABM1 comp = -0.682 dB A/m
BWC Factor = 0.155041 dB
Location: 0, 0, 3.7 mm

0 dB = 405.8

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_PCS _Ch. 1175 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m³
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ⬜⬜⬜ 1 deg C, Liquid T = 22.0 ⬜⬜⬜ 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -8.55 dB A/m
BWC Factor = 0.155041 dB
Location: 6.3, -0.4, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
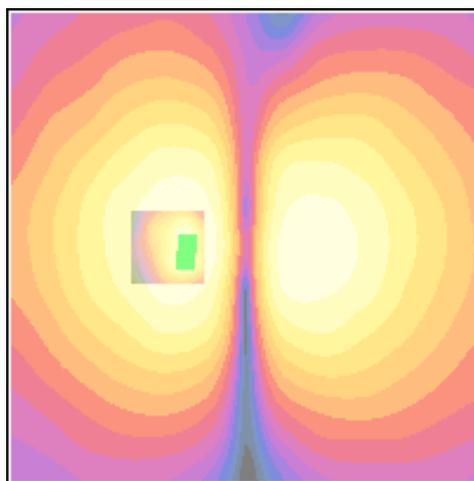Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -8.44 dB A/m
BWC Factor = 0.155041 dB
Location: 6.5, 1.4, 3.7 mm

0 dB = 286.8

Test Laboratory: COMPTEST/KYOCERA   Date: 11/20/2012

FCC_ S2151_TCoil_PCS_ Ch. 1175 y(transversal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.4 dB
ABM1 comp = -8.82 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, 7.9, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
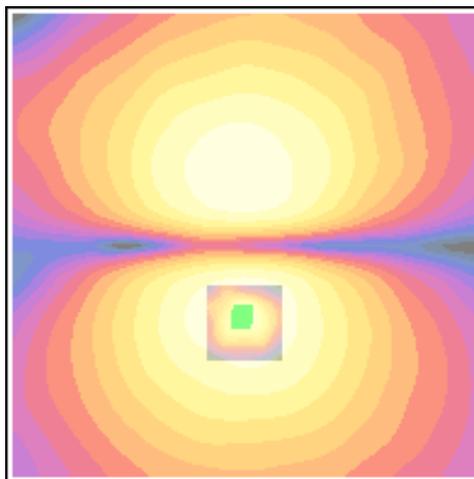Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.3 dB
ABM1 comp = -8.56 dB A/m
BWC Factor = 0.155041 dB
Location: 0, 7.3, 3.7 mm

0 dB = 263.6